PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Satoshi Moriya	01/16/2008
Toshio Saito	01/16/2008
Goichi Yokoyama	01/16/2008
Tsuyoshi Fujiwara	01/16/2008
Hidenori Sato	01/16/2008
Nobuaki Miyakawa	01/16/2008

RECEIVING PARTY DATA

Name:	Hitachi, Ltd.
Street Address:	6-6, Marunouchi 1-chome, Chiyoda-ku,
City:	Tokyo
State/Country:	JAPAN
Postal Code:	100-8280

Name:	Honda Motor Co., Ltd.
Street Address:	1-1, Minami-Aoyama 2-chome, Minato-ku,
City:	Tokyo
State/Country:	JAPAN
Postal Code:	107-8556

OP $40.00 11997436

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11997436

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	843.48479X00
NAME OF SUBMITTER:	Gregory E. Montone

Total Attachments: 2
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ASSIGNMENT
（譲渡証）

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD.
and HONDA MOTOR CO., LTD.,
corporations organized under the laws of Japan,
located at 6-6, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-8280, Japan
and 1-1, Minami-Aoyama 2-chome, Minato-ku, Tokyo 107-8556, Japan
receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD.
and HONDA MOTOR CO., LTD.,
their successors and assigns, all my right, title and interest, in and for the United States of America, in and to

MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE AND SEMICONDUCTOR DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD. and HONDA MOTOR CO., LTD., their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD. and HONDA MOTOR CO., LTD.,

Signed on the date(s) indicated aside our signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	Satoshi Moriya (Satoshi MORIYA)	1/16/2008
2)	Toshio Saito (Toshio SAITO)	1/16/2008
3)	Goichi Yokoyama (Goichi YOKOYAMA)	1/16/2008
4)	Tsuyoshi Fujiwara (Tsuyoshi FUJIWARA)	1/16/2008
5)	Hidenori Sato (Hidenori SATO)	1/16/2008
6)	(Nobuaki MIYAKAWA)	
7)		
8)		

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and HONDA MOTOR CO., LTD.,
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And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.
and HONDA MOTOR CO., LTD.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) （発明者フルネームサイン）	Date Signed （署名日）
1) (Satoshi MORIYA)	
2) (Toshio SAITO)	
3) (Goichi YOKOYAMA)	
4) (Tsuyoshi FUJIWARA)	
5) (Hidenori SATO)	
6) Nobuaki Miyakawa (Nobuaki MIYAKAWA)	January 16 , 2008
7)	
8)	